

REMARKS

This Amendment is in response to the Office Action dated **June 30, 2004**. Each issue is discussed in detail below.

Title

(2)

The title has been amended to reduce its length, as suggested by the Examiner.

Claim Objections

(3-4)

Applicant has made the minor amendments suggested in paragraphs 3 and 4 of the official action.

§112 Rejections

(6)

Claims 10-15 and 19-20 are rejected under 35 USC §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which Applicant regards as the invention. The specific details of the rejection are laid out in 6(a)-6(j).

In response, Applicant has amended the claims to remove the asserted indefinite nature in the claims.

§102 Rejections

(8)

Claims 10 and 19 were rejected under 35 USC §102(b) as being anticipated by Acocella et al. (US 5675889). It is asserted in the rejection that Acocella et al. disclose a method for producing an electronic module as recited in the claims of the present invention comprising the steps: depositing solder cream 13 on the substrate 11 for connecting to the components and transferring the components to the corresponding mounting lands (see Figs. 4 and 6); the connecting the components to the substrate 11. It is noted in the rejection that the components as mention above are readable on 10, 18, etc. Regarding claim 19, it is further asserted that Acocella

et al teach that the module 10 is being connected to the PCB or substrate 11 (see Fig. 6).

Applicant respectfully traverses. The claims above have been amended to address the concerns of the Examiner and more clearly claim the invention. Among the reasons why Acocella et al. do not anticipate the claimed invention is that Acocella et al. do not disclosed surface-mounted components. As seen above, claim 10 has been amended to further clarify this distinction. The device of Acocella et al. does not include surface-mounted components, which are electronic devices which are used to ensure electronic function.

Acocella et al. are teaching the use of Low Melting Temperature (LMT) joining material to solder High Melting Temperature (HMT) spheres onto a substrate. The process described in Acocella et al. is a process to interconnect two substrates by using LMT joining material 13, 16, not soldering pastes, as required by the claims, to solder HMT performs to provide a reliable interconnect assembly. Acocella et al. are not teaching the mounting of surface-mounted components ensuring an electronic function *and* interconnection balls on the same side of a substrate, as required by the claims. Furthermore, Acocella et al. are not teaching simultaneously depositing solder cream for the surface-mounted components and the interconnection or shielding balls, as required by the claim, or to make a single reflow cycle to simultaneously solder surface-mounted components and the interconnection or shielding balls, as required by the claims. As such, Acocella et al. do not disclose each and every element of the rejected claims. Withdrawal of the rejection is therefore respectfully requested.

§103 Rejections

Claims 11-15 and 20 were rejected under 35 USC §103(a) as being unpatentable over Acocella et al. A full recitation of the rejection may be found in numbered paragraph 10, on pages 5-6, of the official action.

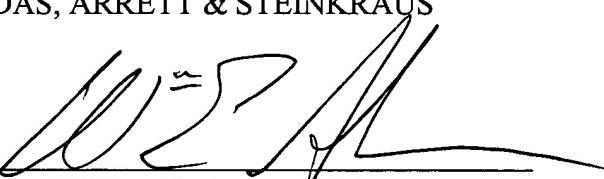
Since claims 11-15 and 20 are dependent upon claim 10 and since the present rejection relies on the rejection as set forth in paragraph 8, among other reasons, the present rejection similarly fails and withdrawal of the rejection is requested.

The application is now believed to be in condition for allowance. If any further issues arise, the Examiner is invited to contact the undersigned.

Respectfully submitted,

VIDAS, ARRETT & STEINKRAUS

By:



William E. Anderson II

Registration No.: 37766

Date: November 29, 2004

6109 Blue Circle Drive, Suite 2000
Minnetonka, MN 55343-9185
Telephone: (952) 563-3000
Facsimile: (952) 563-3001

f:\wpwork\wea\09735us01_amd_20041129.doc